

## Material Declaration Sheet

Vishay General Semiconductor - PDD

Date 16/Sep/15

rart / rroduct ramily Details								
Vishay Part Number	RoHS Compliance Status	RoHS Compliance Date Code dd-mm-yyyy	Total product Weight (gm)	Resistance value	3rd Party Lab ICP Test Report Available	Manufacturing Location	Number of Exemptions Used	
1. 5SMCnn (A) – (H) E3 SM15TnnA-(H) E3 SMCGxx (A) – (H) E3 SMCJxx (A) – (H) E3 SMCJxx (A) – (H) E3 1. 5SMCnnC (A) – (H) E3 SM15TnnCA-(H) E3 SMCGxxC (A) – (H) E3 SMCJxx(A) – (H) E3	YES WITH EXEMPTION	01-12-2004	0. 21	N/A	Yes	China	Two	

Technical Information: refer to http://www.vishay.com/how/leadfree/#summary

Terminal Plating / Grid Array Material	Terminal Base Alloy	JESD-97 Pb-Free Material Code Marking	J-STD-20D MSL Rating	Reflow Peak Process Body Temperature	Reflow Maximum number of cycles	Reflow Max.Time at Peak Temperature (sec)	Soldering Compatibility (SnPb/Pb-Free)
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Material Composition

material composition								
Homogenous Material Name	Material Classification	Substance Name	CAS number	Weight of Substance (gm)	With respect to Homogenous Material		% with respect to Total Product Weight	RoHS Exemptions Used
					%	ppm	Total Troduct weight	
Chip	Electronics (e.g. pc boards, displays)	Silicon and others (business secret)	-	0. 00664	100.00	1000000	3. 16	Exemption No:7(c)-I
Lead Frame	Copper (e.g. copper amounts in cable harnesses)	Copper	7440-50-8	0.07319	100.00	1000000	34. 85	
Solder 92.5	Other special metals	Lead	7439-92-1	0. 00779	92. 50	925000	3. 71	Exemption No:7(a)
		Tin	7440-31-5	0.00042	5.00	50000	0. 20	
		Silver	7440-22-4	0.00021	2.50	25000	0. 10	
Encapsulation	Other duromers	Quartz (SiO2)	14808-60-7	0. 08385	70.00	700000	39. 93	
		Epichlorohydrin, o-cresol, formalde polymer	29690-82-2	0. 01917	16.00	160000	9. 13	
		Phenol-formaldehyde resin	9003-35-4	0. 01436	12.00	120000	6. 84	
		Antimony oxide (Sb2-03)	1309-64-4	0.00120	1.00	10000	0. 57	
		Carbon-Black	1333-86-4	0.00029	0.25	2500	0. 14	
		Additive & know-how	-	0.00090	0.75	7500	0. 43	
Surface finish	Other special metals	Tin	7440-31-5	0.00196	100.00	1000000	0. 93	

EU-RoHS Directive-2011/65/EU MCV of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and MCV of 0.01% by mass cadmium

This MDS vaild for

Exemption Used 7(a) - Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

2nd Exemption Used 7(c)-I - Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

Note :- (i) All information is based on data received from our vendors & subjected to change without prior notice.

(ii) Substance weight are derived from MSDS.



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